

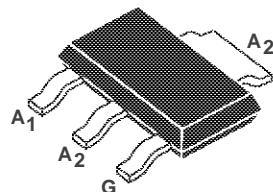
## SENSITIVE GATE TRIACS

### FEATURES

- $I_{T(RMS)} = 1A$
- $V_{DRM} = 400V$  to  $800V$
- $I_{GT} \leq 3mA$  to  $\leq 25mA$

### DESCRIPTION

The Z01xxxN series of triacs uses a high performance TOP GLASS PNPN technology. These parts are intended for general purpose high volume applications using surface mount technology.



**SOT223**  
(Plastic)

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit
$I_{T(RMS)}$	RMS on-state current (360° conduction angle)	1	A
$I_{TSM}$	Non repetitive surge peak on-state current ( $T_j$ initial = 25°C )	$tp = 8.3$ ms	A
		$tp = 10$ ms	
$I^2t$	$I^2t$ Value for fusing	0.35	$A^2s$
$dl/dt$	Critical rate of rise of on-state current $I_G = 50$ mA $dg/dt = 0.1$ A/ $\mu$ s.	Repetitive $F = 50$ Hz	$A/\mu$ s
		Non Repetitive	
$T_{stg}$ $T_j$	Storage and operating junction temperature range	- 40, + 150 - 40, + 125	°C
TI	Maximum lead temperature for soldering during 10s	260	°C

Symbol	Parameter	Voltage				Unit
		D	M	S	N	
$V_{DRM}$ $V_{RRM}$	Repetitive peak off-state voltage $T_j = 125^\circ C$	400	600	700	800	V

## Z01xxxN

### THERMAL RESISTANCES

Symbol	Parameter	Value	Unit
R <sub>th(j-a)</sub>	Junction to ambient	60	°C/W
R <sub>th(j-t)</sub>	Junction to leads for D.C	30	°C/W
R <sub>th(j-t)</sub>	Junction to leads for A.C 360° conduction angle (F=50Hz)	25	°C/W

### GATE CHARACTERISTICS (maximum values)

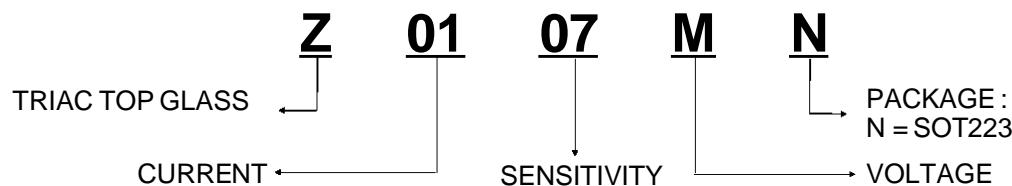
P<sub>G (AV)</sub> = 0.1 W P<sub>GM</sub> = 2 W (tp = 20 μs) I<sub>GM</sub> = 1 A (tp = 20 μs)

### ELECTRICAL CHARACTERISTICS

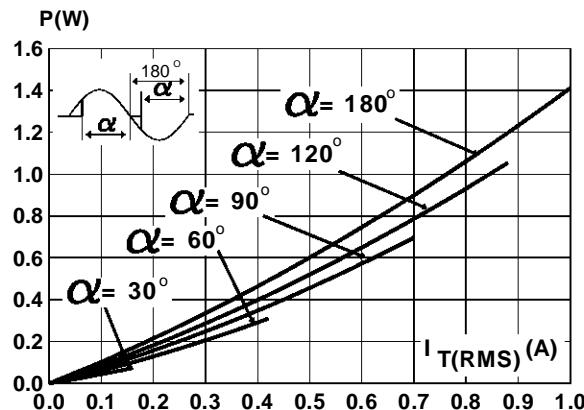
Symbol	Test Conditions	Quadrant		Sensitivity				Unit	
				03	07	09	10		
I <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =140Ω	T <sub>j</sub> = 25°C	I-II-III	MAX	3	5	10	25	mA
			IV	MAX	5	7	10	25	
V <sub>GT</sub>	V <sub>D</sub> =12V (DC) R <sub>L</sub> =140Ω	T <sub>j</sub> = 25°C	I-II-III-IV	MAX	1.5				V
V <sub>GD</sub>	V <sub>D</sub> =V <sub>DRM</sub> R <sub>L</sub> =3.3kΩ	T <sub>j</sub> = 125°C	I-II-III-IV	MIN	0.2				V
tgt	V <sub>D</sub> =V <sub>DRM</sub> I <sub>G</sub> = 40mA I <sub>T</sub> = 1.4A dI <sub>G</sub> /dt = 0.5A/μs	T <sub>j</sub> = 25°C	I-II-III-IV	TYP	2				μs
I <sub>H</sub> *	I <sub>T</sub> = 50 mA Gate open	T <sub>j</sub> = 25°C		MAX	7	10	10	25	mA
I <sub>L</sub>	I <sub>G</sub> = 1.2 I <sub>GT</sub>	T <sub>j</sub> = 25°C	I-III-IV	TYP	7	10	10	25	mA
			II	TYP	14	20	20	50	
V <sub>TM</sub> *	I <sub>TM</sub> = 1.4A tp= 380μs	T <sub>j</sub> = 25°C		MAX	1.8				V
I <sub>DRM</sub> I <sub>RRM</sub>	V <sub>D</sub> = V <sub>DRM</sub> V <sub>R</sub> = V <sub>RRM</sub>	T <sub>j</sub> = 25°C		MAX	10				μA
		T <sub>j</sub> = 110°C		MAX	200				
dV/dt *	V <sub>D</sub> =67%V <sub>DRM</sub> Gate open	T <sub>j</sub> = 110°C		MIN	10	20	50	100	V/μs
(dV/dt)c *	(dI/dt)c = 0.44 A/ms	T <sub>j</sub> = 110°C		MIN			2	5	V/μs
				TYP	1	1			

\* For either polarity of electrode A<sub>2</sub> voltage with reference to electrode A<sub>1</sub>

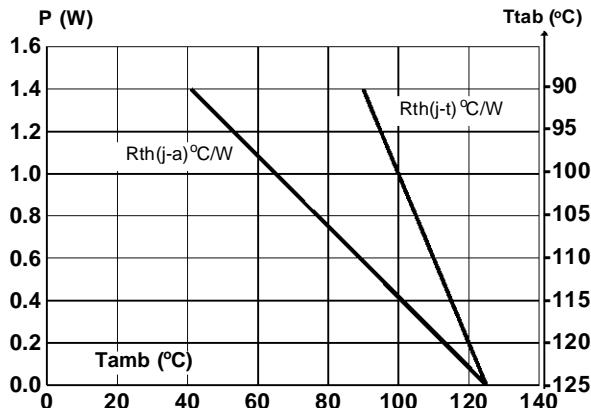
### ORDERING INFORMATION



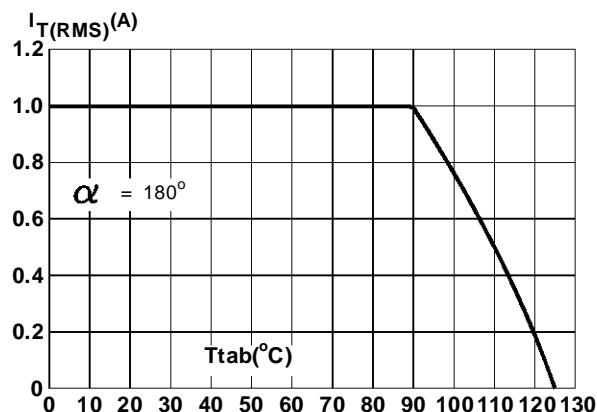
**Fig.1 :** Maximum power dissipation versus RMS on-state current.



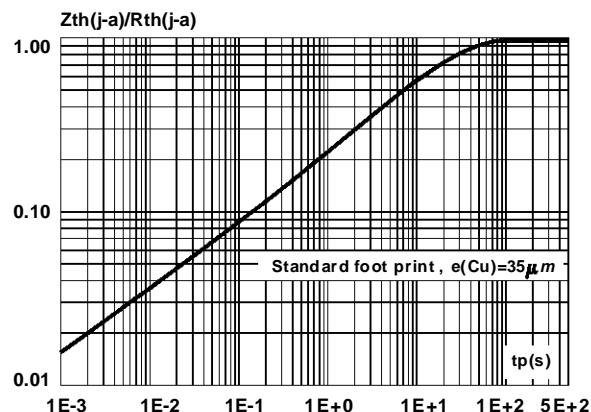
**Fig.2 :** Correlation between maximum power dissipation and maximum allowable temperature (Tamb and Ttab).



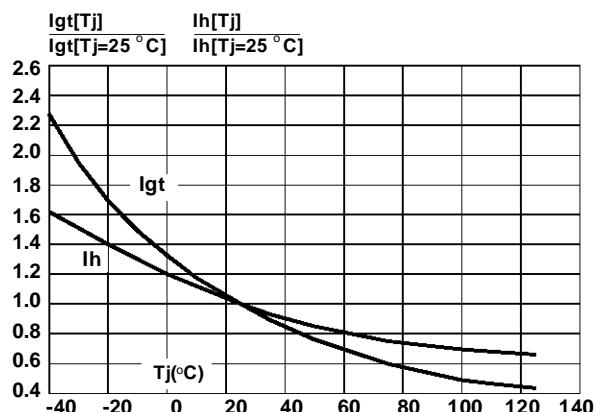
**Fig.3 :** RMS on-state current versus tab temperature.



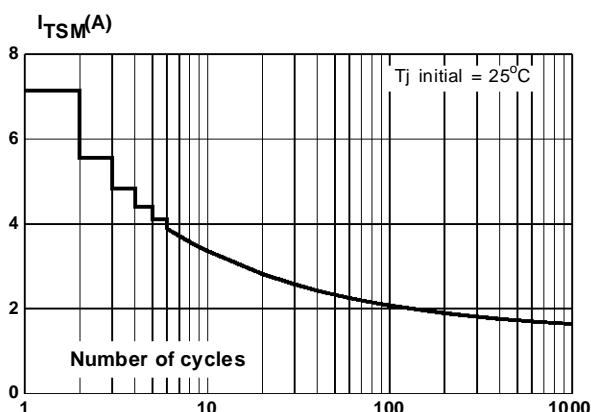
**Fig.4 :** Relative variation of thermal impedance junction to ambient versus pulse duration.



**Fig.5 :** Relative variation of gate trigger current and holding current versus junction temperature.

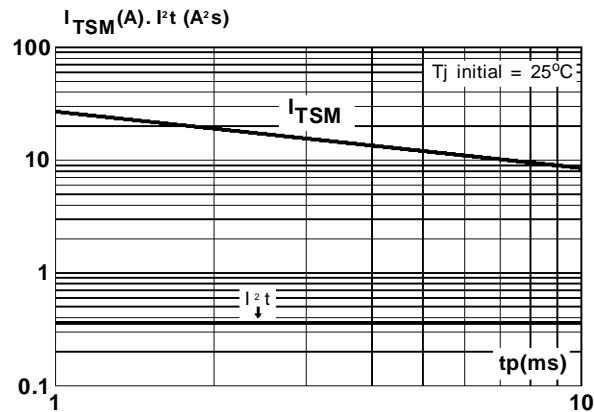


**Fig.6 :** Non repetitive surge peak on-state current versus number of cycles.

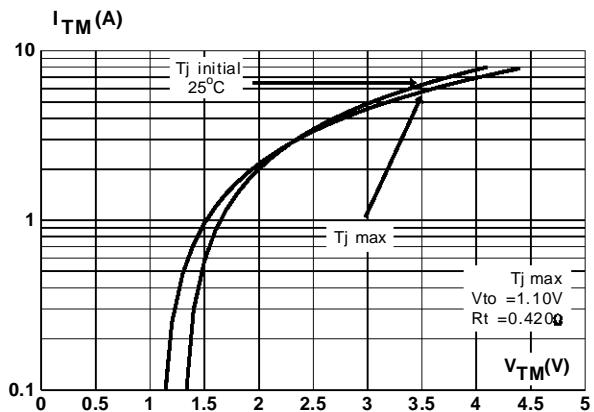


## Z01xxxN

**Fig.7 :** Non repetitive surge peak on-state current for a sinusoidal pulse with width :  $t_p \leq 10\text{ms}$ , and corresponding value of  $I^2t$ .



**Fig.8 :** On-state characteristics (maximum values).

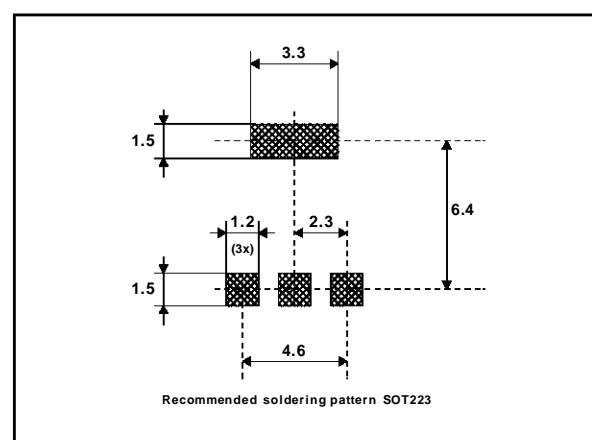


**PACKAGE MECHANICAL DATA**  
SOT223 (Plastic)

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.	Typ.	Max.	Min.	Typ.	Max.
A	6.30	6.50	6.70	0.248	0.256	0.264
B	6.70	7.00	7.30	0.264	0.275	0.287
C	3.30	3.50	3.70	0.130	0.139	0.146
D		4.60			0.181	
E		2.30			0.090	
F	2.90	3.00	3.10	0.114	0.118	0.122
G	0.60	0.70	0.80	0.023	0.027	0.031
H	1.50	1.60	1.70	0.059	0.063	0.067
I	0.43	0.45	0.47	0.017	0.018	0.019
J	0.50	0.60	0.70	0.019	0.023	0.027
K	0.63	0.65	0.67	0.024	0.025	0.026
L		0.05			0.002	
M			0.32			0.012

Weight : 0.11 g

**FOOT PRINT**



## **Z01xxxN**

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### **MARKING**

Type	Marking
Z0103DN	Z3D
Z0103MN	Z3M
Z0103SN	Z3S
Z0103NN	Z3N
Z0107DN	Z7D
Z0107MN	Z7M
Z0107SN	Z7S
Z0107NN	Z7N
Z0109DN	Z9D
Z0109MN	Z9M
Z0109SN	Z9S
Z0109NN	Z9N
Z0110DN	Z0D
Z0110MN	Z0M
Z0110SN	Z0S
Z0110NN	Z0N

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